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### Clean Version of Pending Claims

#### POROUS SILICON OXYCARBIDE INTEGRATED CIRCUIT INSULATOR

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*Claims 49-77 and 79-83, as of September 5, 2002 (date response to first office action filed).*

49. A method, comprising:
- forming a plurality of circuit elements on a substrate;
  - coating at least a portion of a surface of the substrate and at least one of the plurality of circuit elements with a mixture of oxide and carbon sources; and
  - transforming the mixture of oxide and carbon sources into a silicon oxycarbide having uniformly distributed voids that have an approximate diameter between 20 angstroms and 300 angstroms and which has a dielectric constant less than approximately 2.0.
50. The method of claim 49, wherein the mixture of oxide and carbon sources are selected from the group consisting of polymeric precursors, alkoxysilane, silicon alkoxide, methyldimethoxysilane (MDMS), and tetraethoxysilane (TEOS).
51. The method of claim 49, wherein transforming the mixture of oxide and carbon sources includes removing an excess portion of the silicon oxycarbide by chemical mechanical polishing (CMP) to obtain a desired thickness of the silicon oxycarbide.
52. The method of claim 49, wherein transforming includes hydrolyzing the mixture in the presence of an acid.
53. The method of claim 49, wherein transforming includes pyrolyzing the mixture.

54.(Amended) A method, comprising:

providing a plurality of circuit elements on a substrate;  
coating at least a portion of a surface of the substrate with a mixture of oxide and carbon sources;

transforming the mixture of oxide and carbon sources into a first porous oxycarbide glass dielectric layer on the integrated circuit and insulating first and second of the plurality of circuit elements from each other, the first porous oxycarbide glass dielectric layer having uniformly distributed voids that have an approximate diameter between 20 angstroms and 300 angstroms, wherein the first porous oxycarbide glass dielectric layer has a dielectric constant less than approximately 2.0;

selectively forming vias in the first porous oxycarbide glass dielectric layer for providing connection to the first and second circuit elements;

forming metal layers in the vias and elsewhere on a working surface of the substrate;  
patterning and etching the metal layers to provide desired interconnection between the first and second circuit elements and other circuit elements or interconnection lines;

coating at least a portion of a surface of a substrate with a mixture of oxide and carbon sources; and

transforming the mixture of oxide and carbon sources into a second porous oxycarbide glass dielectric layer on the integrated circuit.

55.(Amended) A method , comprising:

providing a plurality of circuit elements on a substrate;  
coating at least a portion of a surface of the substrate with a mixture of oxide and carbon sources;

transforming the mixture of oxide and carbon sources into a first porous oxycarbide glass dielectric layer on the integrated circuit and insulating first and second of the plurality of circuit elements from each other, the first porous oxycarbide glass dielectric layer having voids that have

an approximate diameter between 20 angstroms and 300 angstroms;

selectively forming vias in the first porous oxycarbide glass dielectric layer for providing connection to the first and second circuit elements;

forming metal layers in the vias and elsewhere on a working surface of the substrate;

patterning and etching the metal layers to provide desired interconnection between the first and second circuit elements and other circuit elements or interconnection lines;

coating at least a portion of a surface of a substrate with a mixture of oxide and carbon sources;

transforming the mixture of oxide and carbon sources into a second porous oxycarbide glass dielectric layer on the integrated circuit; and

wherein the second porous oxycarbide glass dielectric layer has a dielectric constant less than approximately 2.0.

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56. The method of claim 55, wherein the second porous oxycarbide glass dielectric layer has uniformly distributed voids that have an approximate diameter between 20 angstroms and 300 angstroms.

57. The method of claim 54, wherein the second porous oxycarbide glass dielectric layer has uniformly distributed voids that have an approximate diameter between 20 angstroms and 300 angstroms.

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58.(Amended) A method, comprising:

providing a plurality of circuit elements on a substrate;

coating at least a portion of a surface of the substrate with a mixture of oxide and carbon sources;

transforming the mixture of oxide and carbon sources into a first porous oxycarbide glass dielectric layer on the integrated circuit and insulating first and second of the plurality of circuit

elements from each other, the first porous oxycarbide glass dielectric layer having voids that have an approximate diameter between 20 angstroms and 300 angstroms;

selectively forming vias in the first porous oxycarbide glass dielectric layer for providing connection to the first and second circuit elements;

forming metal layers in the vias and elsewhere on a working surface of the substrate;

patterning and etching the metal layers to provide desired interconnection between the first and second circuit elements and other circuit elements or interconnection lines;

coating at least a portion of a surface of a substrate with a mixture of oxide and carbon sources;

transforming the mixture of oxide and carbon sources into a second porous oxycarbide glass dielectric layer on the integrated circuit; and

wherein the first porous oxycarbide glass dielectric layer has a dielectric constant less than approximately 2.0.

59.(Amended) A method, comprising:

forming a plurality of circuit elements on a substrate;

coating at least a portion of a surface of the substrate and at least one of the plurality of circuit elements with a mixture of oxide and carbon sources; and

transforming the mixture of oxide and carbon sources into a silicon oxycarbide having uniformly distributed voids that have an approximate diameter between 20 angstroms and 300 angstroms and a dielectric constant less than approximately 2.0.

60. The method of claim 59 wherein the mixture of oxide and carbon sources are selected from the group consisting of polymeric precursors, alkoxysilane, silicon alkoxide, methyltrimethoxysilane (MTMS), and tetraethoxysilane (TEOS).

61. The method of claim 59, wherein transforming the mixture of oxide and carbon sources includes removing an excess portion of the silicon oxycarbide by chemical mechanical polishing (CMP) to obtain a desired thickness of the silicon oxycarbide.

62. The method of claim 59, wherein transforming includes hydrolyzing the mixture in the presence of an acid.

63. The method of claim 59, wherein transforming includes pyrolyzing the mixture.

64.(Amended) A method, comprising:  
forming a plurality of circuit elements on a substrate;  
coating at least a portion of a surface of the substrate and at least one of the plurality of circuit elements with a mixture of oxide and carbon sources; and  
transforming the mixture of oxide and carbon sources into a silicon oxycarbide having uniformly distributed voids that have an approximate diameter of 30 angstroms and a dielectric constant less than approximately 2.0.

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65. The method of claim 64, wherein the mixture of oxide and carbon sources are selected from the group consisting of polymeric precursors, alkoxysilane, silicon alkoxide, methyltrimethoxysilane (MTMS), and tetraethoxysilane (TEOS).

66. The method of claim 64, wherein transforming the mixture of oxide and carbon sources includes removing an excess portion of the silicon oxycarbide by chemical mechanical polishing (CMP) to obtain a desired thickness of the silicon oxycarbide.

67. The method of claim 64, wherein transforming includes hydrolyzing the mixture in the presence of an acid.

68. The method of claim 64, wherein transforming includes pyrolyzing the mixture.
69. A method, comprising:  
forming a plurality of circuit elements on a substrate;  
coating at least a portion of a surface of the substrate and at least one of the plurality of circuit elements with a mixture of oxide and carbon sources; and  
  
transforming the mixture of oxide and carbon sources into a silicon oxycarbide having uniformly distributed voids that have an approximate diameter of 200 angstroms.
70. The method of claim 69, wherein the mixture of oxide and carbon sources are selected from the group consisting of polymeric precursors, alkoxysilane, silicon alkoxide, methyldimethoxysilane (MDMS), and tetraethoxysilane (TEOS).
71. The method of claim 69, wherein transforming the mixture of oxide and carbon sources includes removing an excess portion of the silicon oxycarbide by chemical mechanical polishing (CMP) to obtain a desired thickness of the silicon oxycarbide.
72. The method of claim 69, wherein transforming includes hydrolyzing the mixture in the presence of an acid.
73. The method of claim 69, wherein transforming includes pyrolyzing the mixture.

*Sub C1*  
*B3*

74.(Amended) A method of forming a silicon oxycarbide layer having voids that have an approximate diameter between 20 angstroms and 300 angstroms on a substrate, comprising:  
coating at least a portion the substrate with a mixture of oxide and carbon; and  
transforming the mixture of oxide and carbon sources into the silicon oxycarbide layer  
that has a dielectric constant less than approximately 2.0.

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75. The method of claim 74, wherein coating at least a portion of the substrate includes coating at least one circuit element on the substrate.

76. The method of claim 74, wherein coating at least a portion of the substrate includes coating a plurality of circuit elements on the substrate.

77. A method, comprising:  
coating at least a portion of a surface of the substrate with a mixture of oxide and carbon sources; and  
transforming the mixture of oxide and carbon sources into a silicon oxycarbide having uniformly distributed voids that have an approximate diameter between 20 angstroms and 300 angstroms and which has a dielectric constant less than approximately 2.0.

*Sub C1*  
*B4*

79.(Amended) A method, comprising:  
coating at least a portion of a surface of the substrate with a mixture of oxide and carbon sources; and  
transforming the mixture of oxide and carbon sources into a silicon oxycarbide having uniformly distributed voids that have an approximate diameter of 30 angstroms and having a dielectric constant less than approximately 2.0.

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80. A method, comprising:

coating at least a portion of a surface of the substrate with a mixture of oxide and carbon sources; and

transforming the mixture of oxide and carbon sources into a silicon oxycarbide having uniformly distributed voids that have an approximate diameter of 200 angstroms.

81. The method of claim 54, wherein the second porous oxycarbide glass dielectric layer has a dielectric constant less than approximately 2.0.

82. The method of claim 55, wherein the voids of the second porous oxycarbide glass dielectric layer are uniformly distributed.

83. The method of claim 55, wherein the first porous oxycarbide glass dielectric layer has a dielectric constant less than approximately 2.0.